Document Title

512Kx36-bit, 1Mx18-bit QDR^{TM} SRAM

Revision History

Rev. No.	History	Draft Date	Remark
0.0	1. Initial document.	April 30, 2001	Advance
0.1	1. Amendment 1) Page 3,4 PIN NAME DESCRIPTION $\overline{W}$ (4A) : from Read Control Pin to Write Control $\overline{R}$ (8A) : from Write Control Pin to Read Control BW_0(7B),BW_1(7A),BW_2(5A),BW_3(5B) : from Read Control Pin to Byte Wrtie Control 2) Page 7 STATE DIAGRAM from LEAD NOP to READ NOP	May, 13, 2001	Advance
0.2	1. Amendment 1) Page 8 WRITE TRUTH TABLE(x36) BW_2,BW_3 values for WRITE ALL BYTEs(K↑) and WRITE ALLBYTEs($\overline{K}$↑) : from "H" to " L" 2) Page 13 TIMING WAVE FORMS Note 2 supplement	May, 26, 2001 June, 11, 2001	Advance Advance
0.3	1. 1.8V I/O supply voltage addition 1) Page 2 FEATURES 2) Page 3,4 PIN NAME V_{DDQ} 3) Page 10, OPERATING CONTITIONS 4) Page 11 AC TEST CONTITIONS 2. Amendment 1) Page 15 BOUNDARY SCAN ORDER EXIT		
0.4	1. Icc, Isb addition 2. 1.8V Vddq addition	Sep, 03, 2001	Advance
0.5	1. Reserved pin for high density name change from NC to Vss/SA	Nov, 30, 2001	Preliminary
0.6	1. Release Icc.	May, 22. 2002	Preliminary
1.0	1. Final SPEC release 2. Modify thermal resistance	July, 03. 2002	Final

Rev 0.6 table:

| part #	x18		x36	
	From	To	From	To
-20	500	520	530	600
-16	-	-	490	550
-13	-	-	460	490
-10	-	-	-	-

512Kx36-bit, 1Mx18-bit QDR™ SRAM

FEATURES

- 2.5V+0.1V/-0.1V Power Supply.
- I/O Supply Voltage 1.5V+0.1V/-0.1V for 1.5V I/O,
  1.8V+0.1V/-0.1V for 1.8V I/O.
- Separate independent read and write data ports
  with concurrent read and write operation.
- HSTL I/O.
- Full data coherency, providing most current data .
- Synchronous pipeline read with self timed late write.
- Registered address, control and data input/output.
- DDR(Double Data Rate) Interface on read and write ports.
- Fixed 4-bit burst for both read and write operation.
- Clock-stop supports to reduce current.
- Two input clocks(K and $\overline{K}$) for accurate DDR timing at clock
  rising edges only.
- Two input clocks for output data(C and $\overline{C}$) to minimize
  clock-skew and flight-time mismatches.
- Single address bus.
- Byte writable function.
- Sepatate read/write control pin($\overline{R}$ and $\overline{W}$)
- Simple depth expansion with no data contention.
- Programmable output impedance.
- JTAG 1149.1 compatible test access port.
- 165FBGA(11x15 ball aray FBGA) with body size of 13x15mm

Organization	Part Number	Cycle Time	Access Time	Unit
X36	K7Q163654A-FC20	5.0	2.2	ns
	K7Q163654A-FC16	6.0	2.5	ns
	K7Q163654A-FC13	7.5	3.0	ns
	K7Q163654A-FC10	10.0	3.0	ns
X18	K7Q161854A-FC20	5.0	2.2	ns
	K7Q161854A-FC16	6.0	2.5	ns
	K7Q161854A-FC13	7.5	3.0	ns
	K7Q161854A-FC10	10.0	3.0	ns

FUNCTIONAL BLOCK DIAGRAM
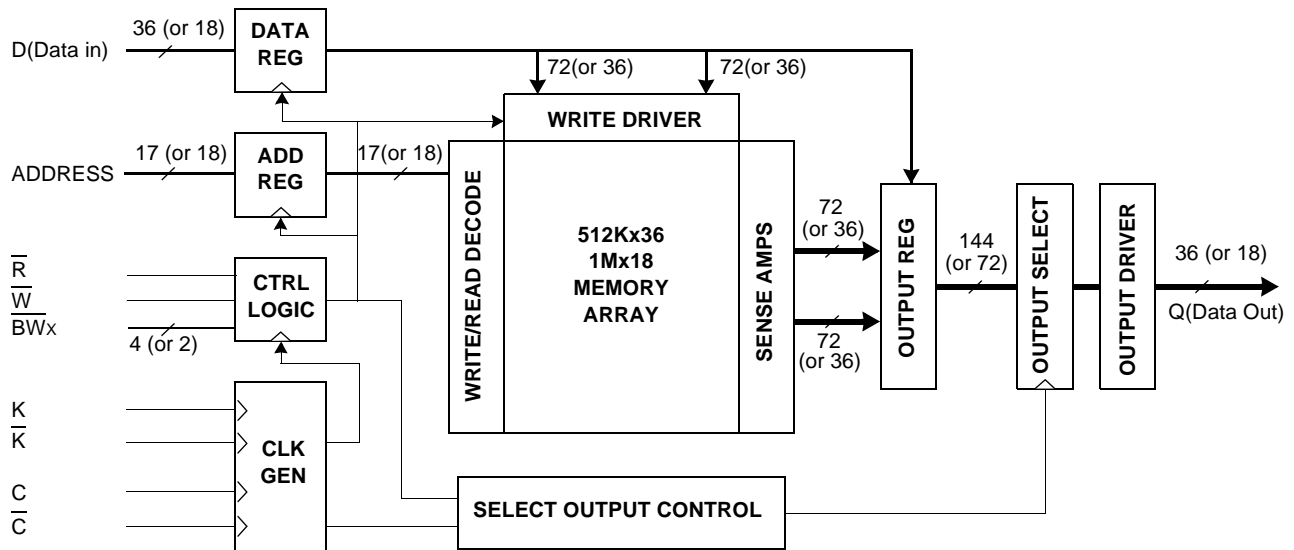
Notes: 1. Numbers in ( ) are for x18 device.

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PIN CONFIGURATIONS(TOP VIEW) **K7Q161854A(1Mx18)**

	1	2	3	4	5	6	7	8	9	10	11
A	NC	Vss/SA*	NC/SA*	$\overline{W}$	$\overline{BW}_1$	$\overline{K}$	NC	$\overline{R}$	SA	Vss/SA*	NC
B	NC	Q9	D9	SA	NC	K	$\overline{BW}_0$	SA	NC	NC	Q8
C	NC	NC	D10	Vss	SA	NC	SA	Vss	NC	Q7	D8
D	NC	D11	Q10	Vss	Vss	Vss	Vss	Vss	NC	NC	D7
E	NC	NC	Q11	VDDQ	Vss	Vss	Vss	VDDQ	NC	D6	Q6
F	NC	Q12	D12	VDDQ	VDD	Vss	VDD	VDDQ	NC	NC	Q5
G	NC	D13	Q13	VDDQ	VDD	Vss	VDD	VDDQ	NC	NC	D5
H	NC	VREF	VDDQ	VDDQ	VDD	Vss	VDD	VDDQ	VDDQ	VREF	ZQ
J	NC	NC	D14	VDDQ	VDD	Vss	VDD	VDDQ	NC	Q4	D4
K	NC	NC	Q14	VDDQ	VDD	Vss	VDD	VDDQ	NC	D3	Q3
L	NC	Q15	D15	VDDQ	Vss	Vss	Vss	VDDQ	NC	NC	Q2
M	NC	NC	D16	Vss	Vss	Vss	Vss	Vss	NC	Q1	D2
N	NC	D17	Q16	Vss	SA	SA	SA	Vss	NC	NC	D1
P	NC	NC	Q17	SA	SA	C	SA	SA	NC	D0	Q0
R	TDO	TCK	SA	SA	SA	$\overline{C}$	SA	SA	SA	TMS	TDI

Notes: 1. * Checked pins are reserved for higher density address, i.e. 3A for 32Mb, 10A for 64Mb and 2A for 128Mb.
    2. BW0 controls write to D0:D8 and BW1 controls write to D9:D17.

PIN NAME

SYMBOL	PIN NUMBERS	DESCRIPTION	NOTES
K, $\overline{K}$	6B, 6A	Input Clock	
C, $\overline{C}$	6P, 6R	Input Clocks for Output data	1
SA	9A,4B,8B,5C,7C,5N-7N,4P,5P,7P,8P,3R-5R,7R-9R	Address Inputs	
D$_{0-17}$	10P,11N,11M,10K,11J,11G,10E,11D,11C,3B,3C,2D, 3F,2G,3J,3L,3M,2N	Data Inputs	
Q$_{0-17}$	11P,10M,11L,11K,10J,11F,11E,10C,11B,2B,3D,3E, 2F,3G,3K,2L,3N,3P	Data Outputs	
$\overline{W}$	4A	Write Control	
$\overline{R}$	8A	Read Control	
$\overline{BW}_0$, $\overline{BW}_1$	7B, 5A	Byte Write Control	
VREF	2H,10H	Input Reference Voltage	
ZQ	11H	Output Driver Impedance Control	2
VDD	5F,7F,5G,7G,5H,7H,5J,7J,5K,7K	Power Supply (2.5V)	
VDDQ	4E,8E,4F,8F,4G,8G,3H,4H,8H,9H,4J,8J,4K,8K,4L,8L	Output Power Supply (1.5V or 1.8V)	
Vss	2A,10A,4C,8C,4D-8D,5E-7E, 6F,6G,6H,6J,6K,5L-7L,4M-8M,4N,8N	Ground	
TMS	10R	JTAG Test Mode Select	
TDI	11R	JTAG Test Data Input	
TCK	2R	JTAG Test Clock	
TDO	1R	JTAG Test Data Output	
NC	1A,3A,7A,11A,1B,5B,9B,10B,1C,2C,6C,9C,1D,9D,10D, 1E,2E,9E,1F,9F,10F,1G,9G,10G,1H,1J,2J,9J,1K,2K, 9J,1L,9L,10L,1M,2M,9M,1N,9N,10N,1P,2P,9P	No Connect	3

Notes: 1. C, $\overline{C}$, K or $\overline{K}$ cannot be set to VREF voltage.
    2. When ZQ pin is directly connected to VDD output impedance is set to minimum value and it cannot be connected to ground or left unconnected.
    3. Not connected to chip pad internally.

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PIN CONFIGURATIONS(TOP VIEW) K7Q163654A(512Kx36)

	1	2	3	4	5	6	7	8	9	10	11
A	NC	Vss/SA*	NC/SA*	$\overline{W}$	$\overline{BW}_2$	$\overline{K}$	$\overline{BW}_1$	$\overline{R}$	NC/SA*	Vss/SA*	NC
B	Q27	Q18	D18	SA	$\overline{BW}_3$	K	$\overline{BW}_0$	SA	D17	Q17	Q8
C	D27	Q28	D19	Vss	SA	NC	SA	Vss	D16	Q7	D8
D	D28	D20	Q19	Vss	Vss	Vss	Vss	Vss	Q16	D15	D7
E	Q29	D29	Q20	VDDQ	Vss	Vss	Vss	VDDQ	Q15	D6	Q6
F	Q30	Q21	D21	VDDQ	VDD	Vss	VDD	VDDQ	D14	Q14	Q5
G	D30	D22	Q22	VDDQ	VDD	Vss	VDD	VDDQ	Q13	D13	D5
H	NC	VREF	VDDQ	VDDQ	VDD	Vss	VDD	VDDQ	VDDQ	VREF	ZQ
J	D31	Q31	D23	VDDQ	VDD	Vss	VDD	VDDQ	D12	Q4	D4
K	Q32	D32	Q23	VDDQ	VDD	Vss	VDD	VDDQ	Q12	D3	Q3
L	Q33	Q24	D24	VDDQ	Vss	Vss	Vss	VDDQ	D11	Q11	Q2
M	D33	Q34	D25	Vss	Vss	Vss	Vss	Vss	D10	Q1	D2
N	D34	D26	Q25	Vss	SA	SA	SA	Vss	Q10	D9	D1
P	Q35	D35	Q26	SA	SA	C	SA	SA	Q9	D0	Q0
R	TDO	TCK	SA	SA	SA	$\overline{C}$	SA	SA	SA	TMS	TDI

Notes: 1. * Checked pins are reserved for higher density address, i.e. 9A for 32Mb, 3A for 64Mb, 10A for 128Mb and 2A for 256Mb.
  2. BW0 controls write to D0:D8, BW1 controls write to D9:D17, BW2 controls write to D18:D26 and BW3 controls write to D27:D35.

PIN NAME

SYMBOL	PIN NUMBERS	DESCRIPTION	NOTES
K, $\overline{K}$	6B, 6A	Input Clock	
C, $\overline{C}$	6P, 6R	Input Clocks for Output data	1
SA	4B,8B,5C,7C,5N-7N,4P,5P,7P,8P,3R-5R,7R-9R	Address Inputs	
D0-35	10P,11N,11M,10K,11J,11G,10E,11D,11C,10N,9M,9L 9J,10G,9F,10D,9C,9B,3B,3C,2D,3F,2G,3J,3L,3M,2N 1C,1D,2E,1G,1J,2K,1M,1N,2P	Data Inputs	
Q0-35	11P,10M,11L,11K,10J,11F,11E,10C,11B,9P,9N,10L 9K,9G,10F,9E,9D,10B,2B,3D,3E,2F,3G,3K,2L,3N 3P,1B,2C,1E,1F,2J,1K,1L,2M,1P	Data Outputs	
$\overline{W}$	4A	Write Control Pin	
$\overline{R}$	8A	Read Control Pin	
$\overline{BW}_0$, $\overline{BW}_1$,$\overline{BW}_2$, $\overline{BW}_3$	7B,7A,5A,5B	Byte Write Control Pin	
VREF	2H,10H	Input Reference Voltage	
ZQ	11H	Output Driver Impedance Control	2
VDD	5F,7F,5G,7G,5H,7H,5J,7J,5K,7K	Power Supply (2.5V)	
VDDQ	4E,8E,4F,8F,4G,8G,3H,4H,8H,9H,4J,8J,4K,8K,4L,8L	Output Power Supply(1.5V or 1.8V)	
Vss	2A,10A,4C,8C,4D-8D,5E-7E, 6F,6G,6H,6J,6K,5L-7L,	Ground	
TMS	10R	JTAG Test Mode Select	
TDI	11R	JTAG Test Data Input	
TCK	2R	JTAG Test Clock	
TDO	1R	JTAG Test Data Output	
NC	1A,3A,9A,11A,6C,1H	No Connect	3

Notes: 1. C, $\overline{C}$, K or $\overline{K}$ cannot be set to VREF voltage.
  2. When ZQ pin is directly connected to VDD output impedance is set to minimum value and it cannot be connected to ground or left unconnected.
  3. Not connected to chip pad internally.

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Rev 1.0

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GENERAL DESCRIPTION

The K7Q163654A and K7Q161854A are 18,874,368-bits QDR(Quad Data Rate) Synchronous Pipelined Burst SRAMs.
They are organized as 524,288 words by 36bits for K7Q163654A and 1,048,576 words by 18 bits for K7Q161854A.

The QDR operation is possible by supporting DDR read and write operations through separate data output and input ports
 with the same cycle. Memory bandwidth is maxmized as data can be transfered into sram
 on every rising edge of K and $\overline{K}$, and transfered out of sram on every rising edge of C and $\overline{C}$.
And totally independent read and write ports eliminate the need for high speed bus turn around.

Address for read and write are latched on alternate rising edges of the input clock K.
Data inputs, and all control signals are synchronized to the input clock (K or $\overline{K}$).
Normally data outputs are synchronized to output clocks (C and $\overline{C}$), but when C and $\overline{C}$ are tied high,
 the data outputs are synchronized to the input clocks (K and $\overline{K}$).
Common address bus is used to access address both for read and write operations.

The internal burst counter is fiexd to 4-bit sequential for both read and write operations, reguiring tow full clock bus cycles.
Any request that attempts to interrupt a burst operation in progress is ignored.
Synchronous pipeline read and late write enable high speed operations.
Simple depth expansion is accomplished by using $\overline{R}$ and $\overline{W}$ for port selection.
Byte write operation is supported with $\overline{BW_0}$ and $\overline{BW_1}$ ($\overline{BW_2}$ and $\overline{BW_3}$) pins.
IEEE 1149.1 serial boundary scan (JTAG) simplifies monitoring package pads attachment status with system.

The K7Q163654A and K7Q161854A are implemented with SAMSUNG's high performance 6T CMOS technology and is available
 in 165pin FBGA packages. Multiple power and ground pins minimize ground bounce.

Read Operations

Read cycles are initiated by activating $\overline{R}$ at the rising edge of the positive input clock K.
Address is presented and stored in the read address register synchronized with K clock.

For 4-bit burst DDR operation, it will access four 36-bit or 18-bit data words with each read command.
The first pipelined data is transfered out of the device triggered by C clock following next K clock rising edge.
Next burst data is triggered by the rising edge of following $\overline{C}$ clock rising edge.
The process continues until all four data are transfered.

Continuous read operations are initiated with K clock rising edge.
And pipelined data are transferred out of device on every rising edge of both C and $\overline{C}$ clocks.
In case C and $\overline{C}$ tied to high, output data are triggered by K and $\overline{K}$ instead of C and $\overline{C}$.

When the $\overline{R}$ is disabled after a read operation, the K7Q163654A and K7Q161854A will first complete burst read operation
before entering into deselect mode at the next K clock rising edge.
Then output drivers disabled automatically to high impedance state.

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Write Operations

Write cycles are initiated by activating $\overline{W}$ at the rising edge of the positive input clock K.
Address is presented and stored in the write address register synchronized with K clock.

For 4-bit burst DDR operation, it will write four 36-bit or 18-bit data words with each write command.
The first "late" data is transfered and registered in to the device synchronous with next K clock rising edge.
Next burst data is transfered and registered synchronous with following $\overline{K}$ clock rising edge.
The process continues until all four data are transfered and registered.

Continuous write operations are initated with K rising edge.
And "late writed" data is presented to the device on every rising edge of both K and $\overline{K}$ clocks.

The device disregards input data presented on the same cycle $\overline{W}$ disabled.
When the $\overline{W}$ is disabled after a read operation, the K7Q163654A and K7Q161854A will first complete burst read operation before
entering into deselect mode at the next K clock rising edge.

The K7Q163654A and K7Q161854A support byte write operations.
With activating $\overline{BW}_0$ or $\overline{BW}_1$ ($\overline{BW}_2$ or $\overline{BW}_3$) in write cycle, only one byte of input data is presented.
In K7Q161854A, $\overline{BW}_0$ controls write operation to D0:D8, $\overline{BW}_1$ controls write operation to D9:D17.
And in K7Q163654A $\overline{BW}_2$ controls write operation to D18:D26, $\overline{BW}_3$ controls write operation to D27:D35.

Programmable Impedance Output Buffer Operation

The designer can program the SRAM's output buffer impedance by terminating the ZQ pin to V_{SS} through a precision resistor(RQ).
The value of RQ (within 15%) is five times the output impedance desired.

For example, 250Ω resistor will give an output impedance of 50Ω.
Impedance updates occur early in cycles that do not activate the outputs, such as deselect cycles.
In all cases impedance updates are transparent to the user and do not produce access time "push-outs"
or other anomalous behavior in the SRAM.

There are no power up requirements for the SRAM. However, to guarantee optimum output driver impedance after power up,
the SRAM needs 1024 non-read cycles.

Single Clock Mode

The K7Q163654A and K7Q161854A can be used with the single clock pair K and $\overline{K}$.
In this mode, C and $\overline{C}$ must be tied high during power up and this single clock pair control both the input and output registers.
C and $\overline{C}$ cannot be tied high during operation.
System flight time and clock skew could not be compensated in single clock mode.

Depth Expansion

Separate input and output ports enables easy depth expansion.
Each port can be selected and deselected independently
and read and write operation do not affect each other.
Before chip deselected, all read and write pending operations are completed.

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STATE DIAGRAM
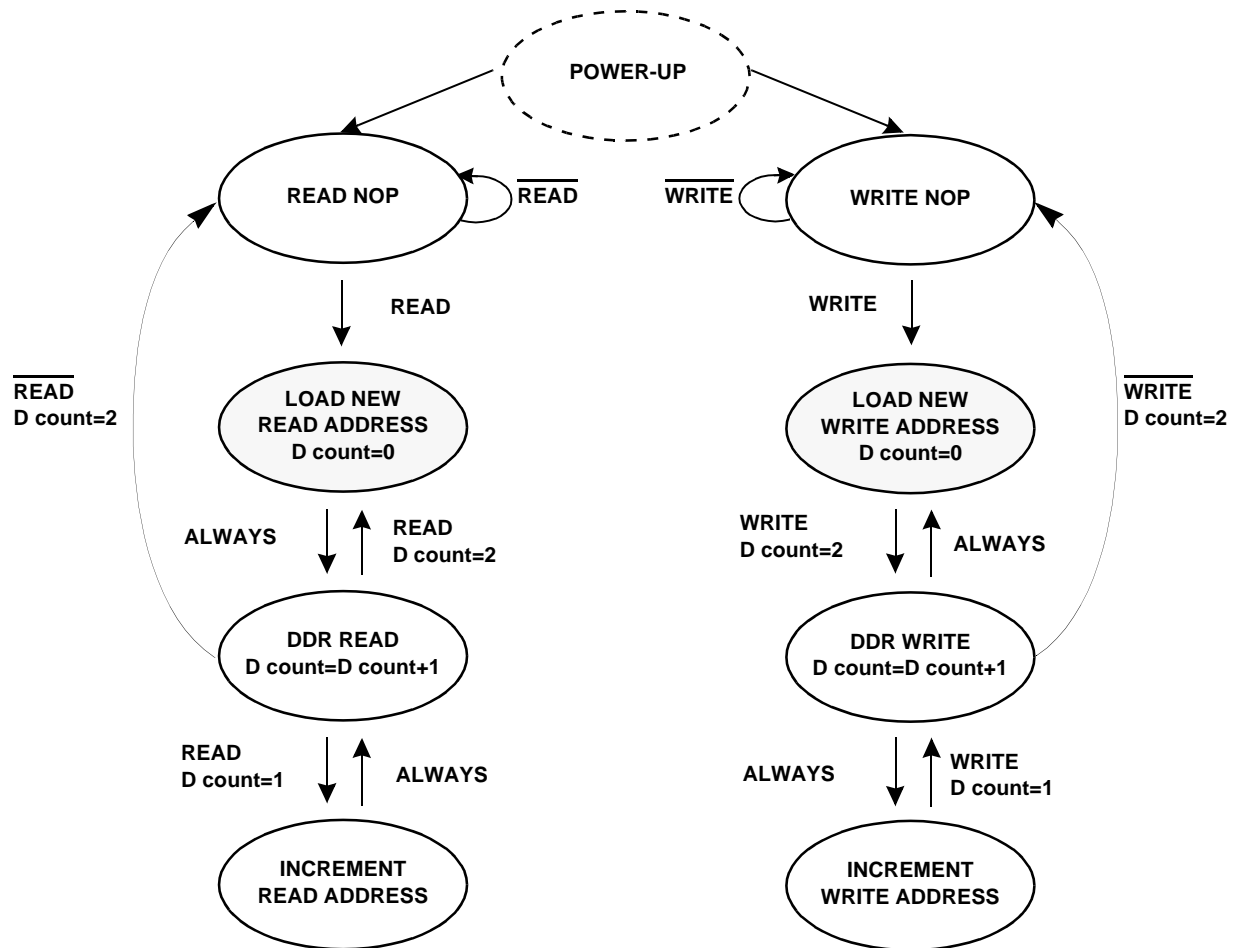
Notes: 1. Internal burst counter is fixed as 2-bit linear, i.e. when first address is A0+0, next internal burst address is A0+1.

2. "READ" refers to read active status with $\overline{R}$=Low, "$\overline{READ}$" refers to read inactive status with $\overline{R}$=high. "WRITE" and "$\overline{WRITE}$" are the same case.

3. Read and write state machine can be active simultaneously.

4. State machine control timing sequence is controlled by K.

TRUTH TABLES

SYNCHRONOUS TRUTH TABLE

K	$\overline{R}$	$\overline{W}$	D				Q				OPERATION
			D(A1)	D(A2)	D(A3)	D(A4)	Q(A1)	Q(A2)	Q(A3)	Q(A4)	
Stopped	X	X	Previous state	Previous state	Previous state	Previous state	Previous state	Previous state	Previous state	Previous state	Clock Stop
↑	H	H	X	X	X	X	High-Z	High-Z	High-Z	High-Z	No Operation
↑	L	X	X	X	X	X	D$_{OUT}$ at C(t+1)	D$_{OUT}$ at $\overline{C}$(t+1)	D$_{OUT}$ at C(t+2)	D$_{OUT}$ at $\overline{C}$(t+2)	Read
↑	H	L	Din at K(t+1)	Din at $\overline{K}$(t+1)	Din at K(t+2)	Din at $\overline{K}$(t+2)	X	X	X	X	Write

Notes: 1. X means "Don't Care".
2. The rising edge of clock is symbolized by (↑).
3. Before enter into clock stop status, all pending read and write operations will be completed.

WRITE TRUTH TABLE(x18)

K	$\overline{K}$	$\overline{W}$	$\overline{BW_0}$	$\overline{BW_1}$	OPERATION
↑		H	X	X	READ/NOP
	↑	H	X	X	READ/NOP
↑		L	L	L	WRITE ALL BYTEs (K↑)
	↑	L	L	L	WRITE ALL BYTEs ($\overline{K}$↑)
↑		L	L	H	WRITE BYTE 0 (K↑)
	↑	L	L	H	WRITE BYTE 0 ($\overline{K}$↑)
↑		L	H	L	WRITE BYTE 1 (K↑)
	↑	L	H	L	WRITE BYTE 1 ($\overline{K}$↑)
↑		L	H	H	WRITE NOTHING (K↑)
	↑	L	H	H	WRITE NOTHING ($\overline{K}$↑)

Notes: 1. X means "Don't Care".
2. All inputs in this table must meet setup and hold time around the rising edge of CLK(↑).

WRITE TRUTH TABLE(x36)

K	$\overline{K}$	$\overline{W}$	$\overline{BW_0}$	$\overline{BW_1}$	$\overline{BW_2}$	$\overline{BW_3}$	OPERATION
↑		H	X	X	X	X	READ/NOP
	↑	H	X	X	X	X	READ/NOP
↑		L	L	L	L	L	WRITE ALL BYTEs (K↑)
	↑	L	L	L	L	L	WRITE ALL BYTEs ($\overline{K}$↑)
↑		L	L	H	H	H	WRITE BYTE 0 (K↑)
	↑	L	L	H	H	H	WRITE BYTE 0 ($\overline{K}$↑)
↑		L	H	L	H	H	WRITE BYTE 1 (K↑)
	↑	L	H	L	H	H	WRITE BYTE 1 ($\overline{K}$↑)
↑		L	H	H	L	L	WRITE BYTE 2 and BYTE 3 (K↑)
	↑	L	H	H	L	L	WRITE BYTE 2 and BYTE 3 ($\overline{K}$↑)
↑		L	H	H	H	H	WRITE NOTHING (K↑)
	↑	L	H	H	H	H	WRITE NOTHING ($\overline{K}$↑)

Notes: 1. X means "Don't Care".
2. All inputs in this table must meet setup and hold time around the rising edge of CLK(↑).

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ABSOLUTE MAXIMUM RATINGS*

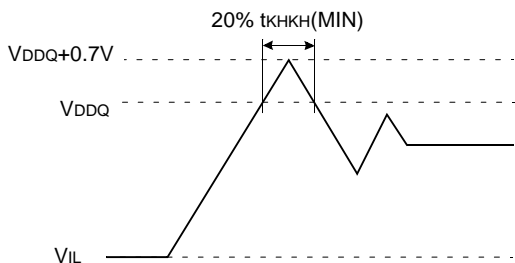| PARAMETER	SYMBOL	RATING	UNIT
Voltage on V$_{DD}$ Supply Relative to V$_{SS}$	V$_{DD}$	-0.5 to 3.6	V
Voltage on V$_{DDQ}$ Supply Relative to V$_{SS}$	V$_{DDQ}$	-0.5 to V$_{DD}$	V
Voltage on Input Pin Relative to V$_{SS}$	V$_{IN}$	-0.5 to V$_{DD}$+0.3	V
Power Dissipation	P$_D$	1.8	W
Storage Temperature	T$_{STG}$	-65 to 150	°C
Operating Temperature	T$_{OPR}$	0 to 70	°C
Storage Temperature Range Under Bias	T$_{BIAS}$	-10 to 85	°C

*Note: 1. Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating
   only and functional operation of the device at these or any other conditions above those indicated in the operating sections of this specification
   is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

2. V$_{DDQ}$ must not exceed V$_{DD}$ during normal operation.

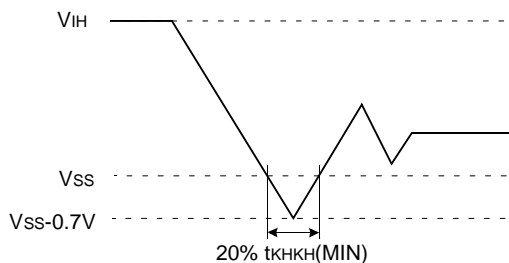## DC ELECTRICAL CHARACTERISTICS (V$_{DD}$=2.5V ±0.1V, T$_A$=0°C to +70°C)

PARAMETER	SYMBOL	TEST CONDITIONS		MIN	MAX	UNIT	NOTES
Input Leakage Current	I$_{IL}$	V$_{DD}$=Max ; V$_{IN}$=V$_{SS}$ to V$_{DDQ}$		-2	+2	µA	
Output Leakage Current	I$_{OL}$	Output Disabled,		-2	+2	µA	
Operating Current (x18) : DDR	I$_{CC}$	V$_{DD}$=Max , I$_{OUT}$=0mA Cycle Time ≥ t$_{KHKH}$ Min	-20	-	520	mA	1,5
			-16	-	460		
			-13	-	430		
			-10	-	390		
Operating Current (x36) : DDR	I$_{CC}$	V$_{DD}$=Max , I$_{OUT}$=0mA Cycle Time ≥ t$_{KHKH}$ Min	-20	-	600	mA	1,5
			-16	-	550		
			-13	-	490		
			-10	-	420		
Standby Current(NOP) : DDR	I$_{SB1}$	Device deselected, I$_{OUT}$=0mA, f=Max, All Inputs≤0.2V or ≥ V$_{DD}$-0.2V	-20	-	200	mA	1,6
			-16	-	190		
			-13	-	180		
			-10	-	170		
Output High Voltage	V$_{OH1}$			V$_{DDQ}$/2	V$_{DDQ}$	V	2,7
Output Low Voltage	V$_{OL1}$			V$_{SS}$	V$_{DDQ}$/2	V	3,7
Output High Voltage	V$_{OH2}$	I$_{OH}$=-1.0mA		V$_{DDQ}$-0.2	V$_{DDQ}$	V	4
Output Low Voltage	V$_{OL2}$	I$_{OL}$=1.0mA		V$_{SS}$	0.2	V	4
Input Low Voltage	V$_{IL}$			-0.3	V$_{REF}$-0.1	V	8,9
Input High Voltage	V$_{IH}$			V$_{REF}$+0.1	V$_{DDQ}$+0.3	V	8,10

Notes: 1. Minimum cycle. I$_{OUT}$=0mA.
   2. |I$_{OH}$|=(V$_{DDQ}$/2)/(RQ/5)±15% @V$_{OH}$=V$_{DDQ}$/2 for 175Ω ≤ RQ ≤ 350Ω.
   3. |I$_{OL}$|=(V$_{DDQ}$/2)/(RQ/5)±15% @V$_{OL}$=V$_{DDQ}$/2 for 175Ω ≤ RQ ≤ 350Ω.
   4. Minimum Impedance Mode when ZQ pin is connected to V$_{SS}$.
   5. Operating current is calculated with 50% read cycles and 50% write cycles.
   6. Standby Current is only after all pending read and write burst opeactions are completed.
   7. Programmable Impedance Mode.
   8. These are DC test criteria. DC design criteria is V$_{REF}$±50mV. The AC V$_{IH}$/V$_{IL}$ levels are defined separately for measuring
       timing parameters.
   9. V$_{IL}$ (Min)DC=-0.3V, V$_{IL}$ (Min)AC=-1.5V(pulse width ≤ 3ns).
   10. V$_{IH}$ (Max)DC=V$_{DDQ}$+0.3, V$_{IH}$ (Max)AC=V$_{DDQ}$+0.85V(pulse width ≤ 3ns).

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Overershoot Timing

20% tKHKH(MIN)

VDDQ+0.7V

VDDQ

VIL

Undershoot Timing

VIH

VSS

VSS-0.7V

20% tKHKH(MIN)

Note: For power-up, VIH ≤ VDDQ+0.3V and VDD ≤ 2.4V and VDDQ ≤ 1.4V for t ≤ 200ms

OPERATING CONDITIONS (0°C ≤ TA ≤ 70°C)

PARAMETER	SYMBOL	MIN	MAX	UNIT
Supply Voltage	VDD	2.4	2.6	V
	VDDQ	1.4	1.9	V
Reference Voltage	VREF	0.68	0.95	V
Ground	VSS	0	0	V

AC TIMING CHARACTERISTICS(VDD=2.5V±0.1V, TA=0°C to +70°C)

| PARAMETER	SYMBOL	-20 MIN	-20 MAX	-16 MIN	-16 MAX	-13 MIN	-13 MAX	-10 MIN	-10 MAX	UNITS	NOTES
Clock											
Clock Cycle Time(K, $\overline{K}$, C, $\overline{C}$)	tKHKH	5		6		7.5		10		ns	
Clock HIGH time (K, $\overline{K}$, C, $\overline{C}$)	tKHKL	2.0		2.4		3.0		3.5		ns	
Clock LOW time (K, $\overline{K}$, C, $\overline{C}$)	tKLKH	2.0		2.4		3.0		3.5		ns	
Clock to clock (K↑→$\overline{K}$↑, C↑→$\overline{C}$↑)	tKH$\overline{K}$H	2.2	2.75	2.7	3.3	3.4	4.1	4.6	5.4	ns	
Clock to data clock (K↑→C↑, $\overline{K}$↑→$\overline{C}$↑)	tKHCH	0.0	1.7	0.0	2.0	0.0	2.5	0.0	3.0	ns	
Output Times											
C, $\overline{C}$ High to Output Valid	tCHQV		2.2		2.5		3.0		3.0	ns	3
C, $\overline{C}$ High to Output hold	tCHQX	1.0		1.2		1.2		1.2		ns	3
C High to Output High-Z	tCHQZ		2.2		2.5		3.0		3.0	ns	3
C High to Output Low-Z	tCHQX1	1.0		1.2		1.2		1.2		ns	3
Setup Times											
Address valid to K rising edge	tAVKH	0.6		0.7		0.8		1.0		ns	
Control inputs valid to K rising edge	tIVKH	0.6		0.7		0.8		1.0		ns	2
Data-in valid to K, $\overline{K}$ rising edge	tDVKH	0.6		0.7		0.8		1.0		ns	
Hold Times											
K rising edge to address hold	tKHAX	0.6		0.7		0.8		1.0		v	
K rising edge to control inputs hold	tKHIX	0.6		0.7		0.8		1.0		ns	
K, $\overline{K}$ rising edge to data-in hold	tKHDX	0.6		0.7		0.8		1.0		ns	

Notes: 1. All address inputs must meet the specified setup and hold times for all latching clock edges.
2. Control signals are R, W, BW0, BW1 and (BW2, BW3, also for x36)
3. If C, $\overline{C}$ are tied high, K, $\overline{K}$ become the references for C, $\overline{C}$ timing parameters.
4. To avoid bus contention, at a given voltage and temperature tCHQX1 is bigger than tCHQZ.
   The specs as shown do not imply bus contention beacuse tCHQX1 is a MIN parameter that is worst case at totally different test conditions
   (0°C, 2.6V) than tCHQZ, which is a MAX parameter(worst case at 70°C, 2.4V)
   It is not possible for two SRAMs on the same board to be at such different voltage and temperature.

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AC TEST CONDITIONS

Parameter	Symbol	Value	Unit
Core Power Supply Voltage	V_{DD}	2.4~2.6	V
Output Power Supply Voltage	V_{DDQ}	1.4~1.9	V
Input High/Low Level	V_{IH}/V_{IL}	1.25/0.25	V
Input Reference Level	V_{REF}	0.75	V
Input Rise/Fall Time	T_R/T_F	0.3/0.3	ns
Output Timing Reference Level		$V_{DDQ}/2$	V

Note: Parameters are tested with RQ=250Ω

AC TEST OUTPUT LOAD
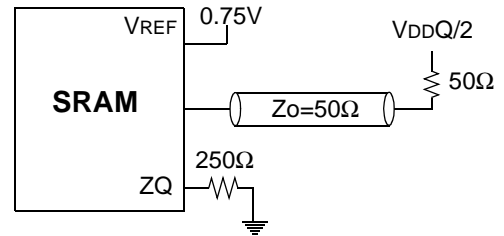
PIN CAPACITANCE

PRMETER	SYMBOL	TESTCONDITION	MIN	MAX	Unit	NOTES
Address Control Input Capacitance	C_{IN}	V_{IN}=0V	4	5	pF	
Input and Output Capacitance	C_{OUT}	V_{OUT}=0V	6	7	pF	
Clock Capacitance	C_{CLK}	-	5	6	pF	

Note: 1. Parameters are tested with RQ=250Ω and V_{DDQ}=1.5V.

2. Periodically sampled and not 100% tested.

THERMAL RESISTANCE

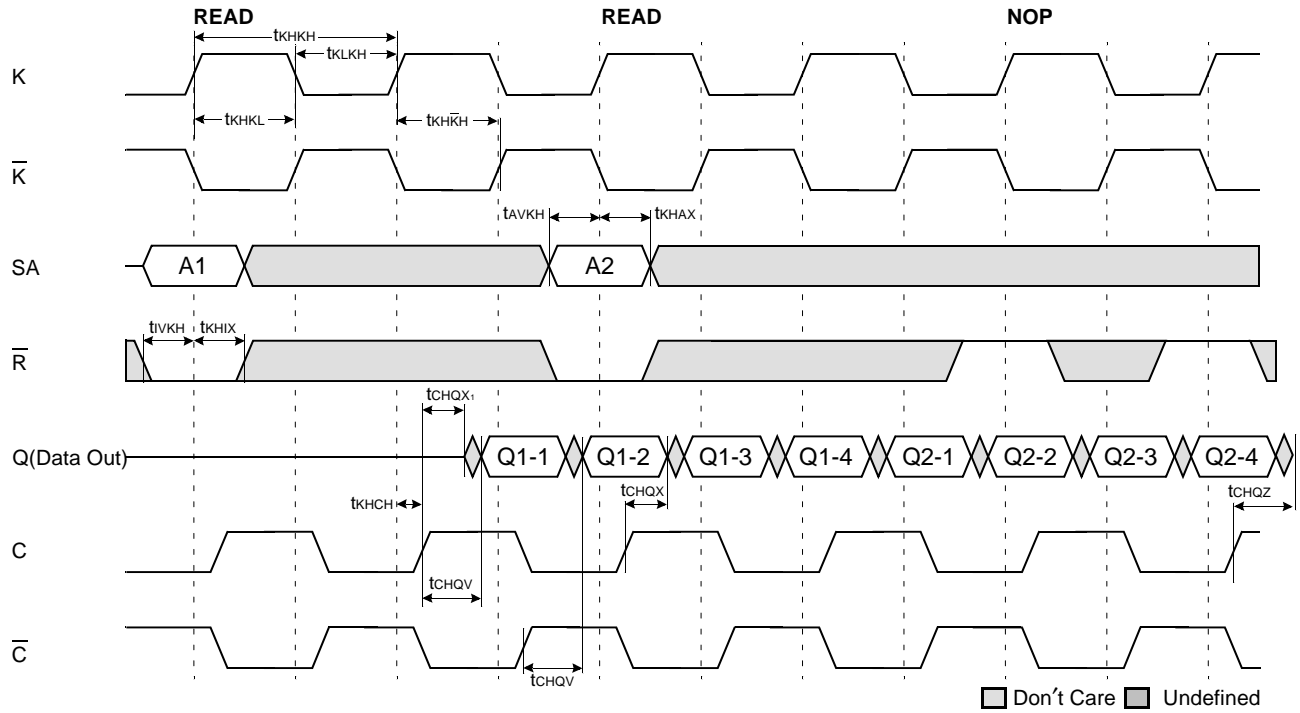| PRMETER	SYMBOL	TYP	Unit	NOTES
Junction to Ambient	θ_{JA}	24.0	°C/W	
Junction to Case	θ_{JC}	2.8	°C/W	
Junction to Pins	θ_{JB}	5.5	°C/W	

Note: Junction temperature is a function of on-chip power dissipation, package thermal impedance, mounting site temperature and mounting site thermal impedance. $T_J=T_A + P_D \times \theta_{JA}$

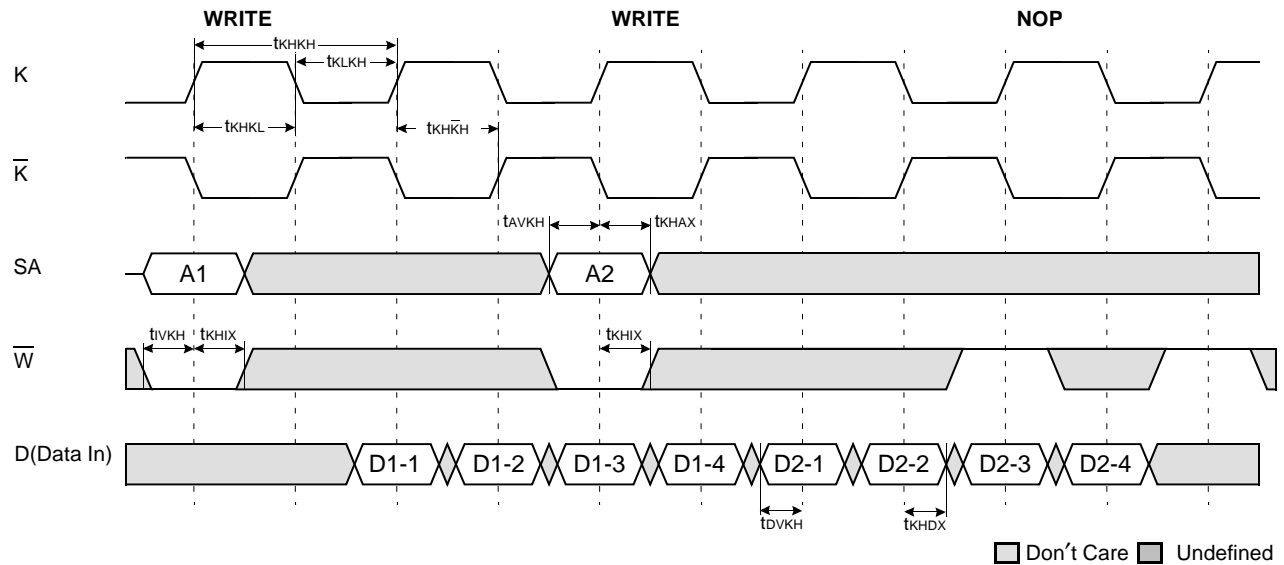## APPLICATION INFORMATION

1Mx18
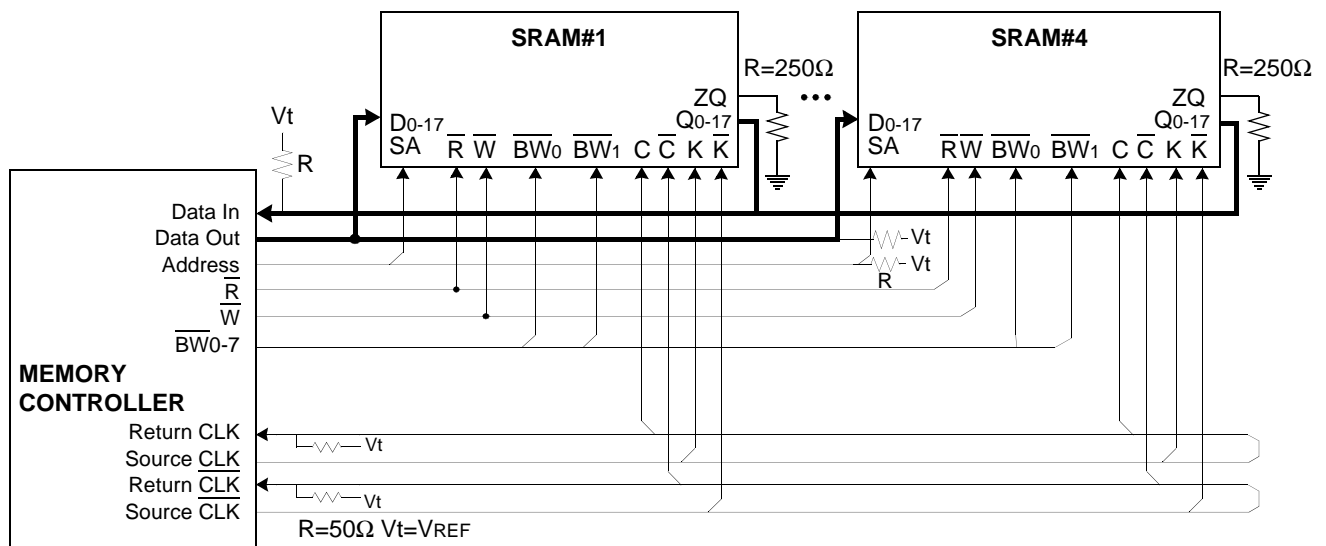
TIMING WAVE FORMS OF READ AND NOP

Note: 1. Q1-1 refers to output from address A1+0, Q1-2 refers to output from address A1+1 i.e. the next internal burst address following A1+0.

2. Outputs are disabled one cycle after a NOP.

TIMING WAVE FORMS OF WRITE AND NOP

Note: 1. D1-1 refers to input to address A1+0, D1-2 refers to input to address A1+1, i.e the next internal burst address following A1+0.

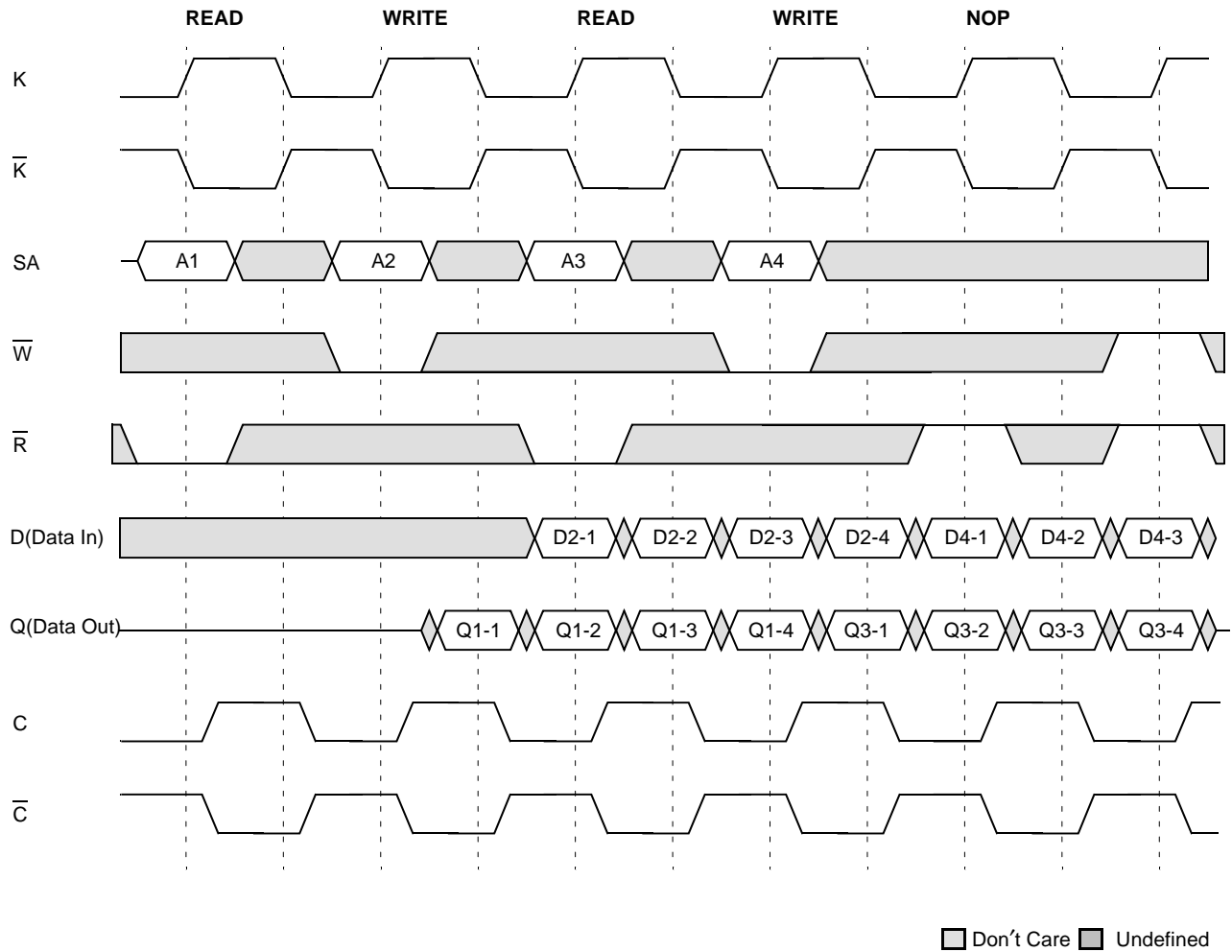## TIMING WAVE FORMS OF READ, WRITE AND NOP

Don't Care ☐   Undefined ☐

**Note**: 1. Q1-1 refers to output from address A1+0, Q1-2 refers to output from address A1+1 i.e. the next internal burst address following A1+0.

2. Outputs are disabled one cycle after a NOP.

3. If address A3=A2, data Q3-1=D2-1, data Q3-2=D2-2,data Q3-3=D2-3, data Q3-4=D2-4.
    Write data is forwarded immediately as read results.

4. $\overline{BW}$x assumed active

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IEEE 1149.1 TEST ACCESS PORT AND BOUNDARY SCAN-JTAG

This part contains an IEEE standard 1149.1 Compatible Test Access Port(TAP). The package pads are monitored by the Serial Scan circuitry when in test mode. This is to support connectivity testing during manufacturing and system diagnostics. Internal data is not driven out of the SRAM under JTAG control. In conformance with IEEE 1149.1, the SRAM contains a TAP controller, Instruction Register, Bypass Register and ID register. The TAP controller has a standard 16-state machine that resets internally upon power-up, therefore, TRST signal is not required. It is possible to use this device without utilizing the TAP. To disable the TAP controller without interfacing with normal operation of the SRAM, TCK must be tied to Vss to preclude mid level input. TMS and TDI are designed so an undriven input will produce a response identical to the application of a logic 1, and may be left unconnected. But they may also be tied to VDD through a resistor. TDO should be left unconnected.

JTAG Block Diagram
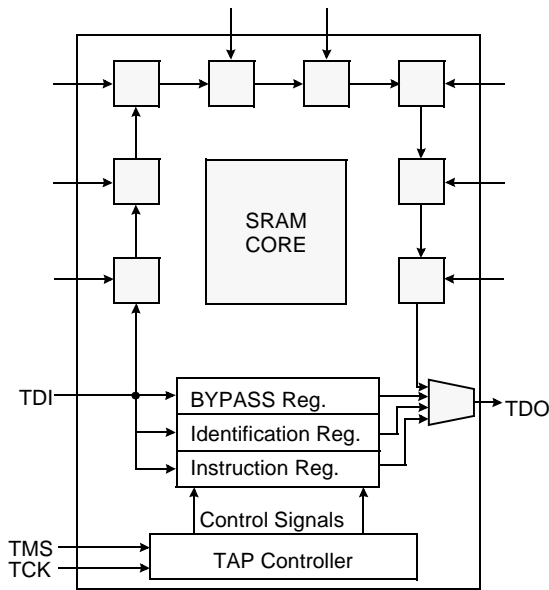
JTAG Instruction Coding

IR2	IR1	IR0	Instruction	TDO Output	Notes
0	0	0	EXTEST	Boundary Scan Register	1
0	0	1	IDCODE	Identification Register	3
0	1	0	SAMPLE-Z	Boundary Scan Register	2
0	1	1	BYPASS	Bypass Register	4
1	0	0	SAMPLE	Boundary Scan Register	5
1	0	1	RESERVED	Do Not Use	6
1	1	0	BYPASS	Bypass Register	4
1	1	1	BYPASS	Bypass Register	4

NOTE :

1. Places DQs in Hi-Z in order to sample all input data regardless of other SRAM inputs. This instruction is not IEEE 1149.1 compliant.

2. Places DQs in Hi-Z in order to sample all input data regardless of other SRAM inputs.

3. TDI is sampled as an input to the first ID register to allow for the serial shift of the external TDI data.

4. Bypass register is initiated to Vss when BYPASS instruction is invoked. The Bypass Register also holds serially loaded TDI when exiting the Shift DR states.

5. SAMPLE instruction dose not places DQs in Hi-Z.

6. This instruction is reserved for future use.

TAP Controller State Diagram

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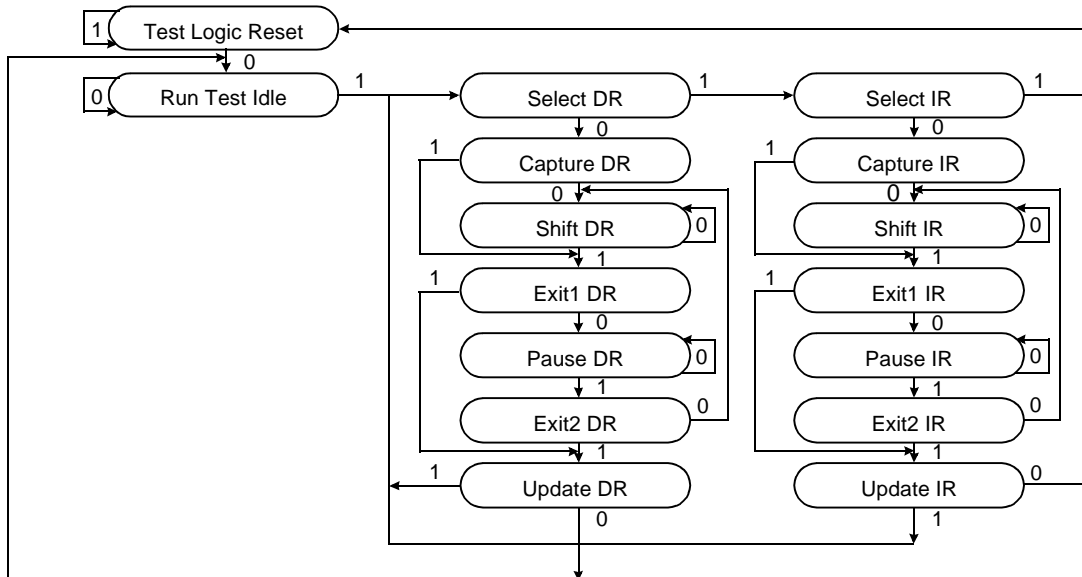
SCAN REGISTER DEFINITION

Part	Instruction Register	Bypass Register	ID Register	Boundary Scan
1Mx18	3 bits	1 bits	32 bits	107 bits
512Kx36	3 bits	1 bits	32 bits	107 bits

ID REGISTER DEFINITION

Part	Revision Number (31:28)	Part Configuration (27:18)	Vendor Definition (17:12)	Samsung JEDEC Code (11: 1)	Start Bit(0)
1Mx18	0000	01000 00011	XXXXXX	00001001110	1
512Kx36	0000	00111 00100	XXXXXX	00001001110	1

BOUNDARY SCAN EXIT ORDER

BIT	PIN ID	BIT	PIN ID	BIT	PIN ID
1	6R	37	10D	73	2C
2	6P	38	9E	74	3E
3	6N	39	10C	75	2D
4	7P	40	11D	76	2E
5	7N	41	9C	77	1E
6	7R	42	9D	78	2F
7	8R	43	11B	79	3F
8	8P	44	11C	80	1G
9	9R	45	9B	81	1F
10	11P	46	10B	82	3G
11	10P	47	11A	83	2G
12	10N	48	10A	84	1J
13	9P	49	9A	85	2J
14	10M	50	8B	86	3K
15	11N	51	7C	87	3J
16	9M	52	6C	88	2K
17	9N	53	8A	89	1K
18	11L	54	7A	90	2L
19	11M	55	7B	91	3L
20	9L	56	6B	92	1M
21	10L	57	6A	93	1L
22	11K	58	5B	94	3N
23	10K	59	5A	95	3M
24	9J	60	4A	96	1N
25	9K	61	5C	97	2M
26	10J	62	4B	98	3P
27	11J	63	3A	99	2N
28	11H	64	2A	100	2P
29	10G	65	1A	101	1P
30	9G	66	2B	102	3R
31	11F	67	3B	103	4R
32	11G	68	1C	104	4P
33	9F	69	1B	105	5P
34	10F	70	3D	106	5N
35	11E	71	3C	107	5R
36	10E	72	1D		

Note: 1. NC pins are read as "X" (i.e. don't care.)

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JTAG DC OPERATING CONDITIONS

Parameter	Symbol	Min	Typ	Max	Unit	Note
Power Supply Voltage	V_{DD}	2.4	2.5	2.6	V	
Input High Level	V_{IH}	1.7	-	V_{DD}+0.3	V	
Input Low Level	V_{IL}	-0.3	-	0.7	V	
Output High Voltage(I_{OH}=-2mA)	V_{OH}	2.0	-	V_{DD}	V	
Output Low Voltage(I_{OL}=2mA)	V_{OL}	V_{SS}	-	0.4	V	

Note: 1. The input level of SRAM pin is to follow the SRAM DC specification.

JTAG AC TEST CONDITIONS

Parameter	Symbol	Min	Unit	Note
Input High/Low Level	V_{IH}/V_{IL}	2.5/0.0	V	
Input Rise/Fall Time	TR/TF	1.0/1.0	ns	
Input and Output Timing Reference Level		1.25	V	1

**Note**: 1. See SRAM AC test output load on page 11.

JTAG AC Characteristics

Parameter	Symbol	Min	Max	Unit	Note
TCK Cycle Time	t_{CHCH}	50	-	ns	
TCK High Pulse Width	t_{CHCL}	20	-	ns	
TCK Low Pulse Width	t_{CLCH}	20	-	ns	
TMS Input Setup Time	t_{MVCH}	5	-	ns	
TMS Input Hold Time	t_{CHMX}	5	-	ns	
TDI Input Setup Time	t_{DVCH}	5	-	ns	
TDI Input Hold Time	t_{CHDX}	5	-	ns	
SRAM Input Setup Time	t_{SVCH}	5	-	ns	
SRAM Input Hold Time	t_{CHSX}	5	-	ns	
Clock Low to Output Valid	t_{CLQV}	0	10	ns	

JTAG TIMING DIAGRAM

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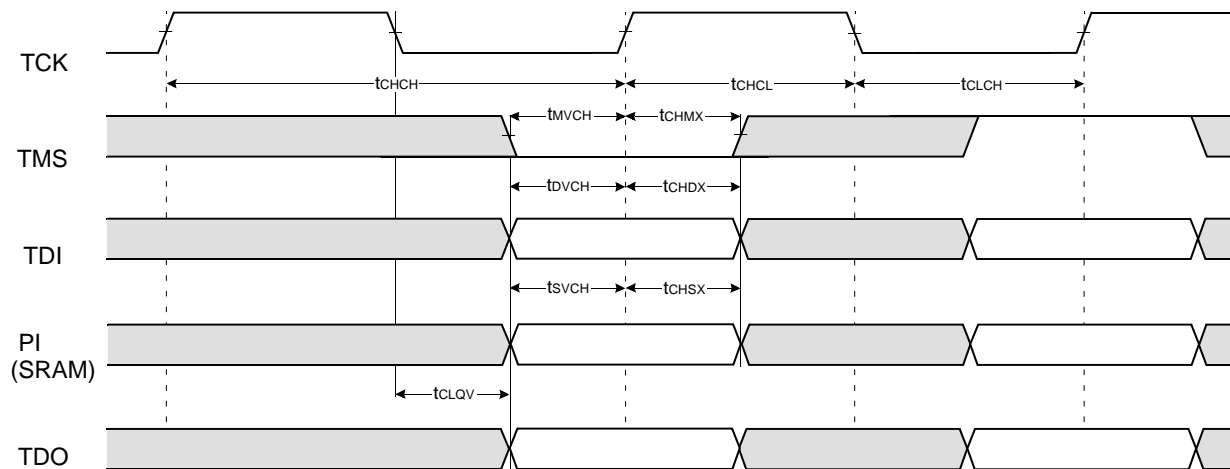
165 FBGA PACKAGE DIMENSIONS

13mm x 15mm Body, 1.0mm Bump Pitch, 11x15 Ball Array

Top View

Side View

Bottom View
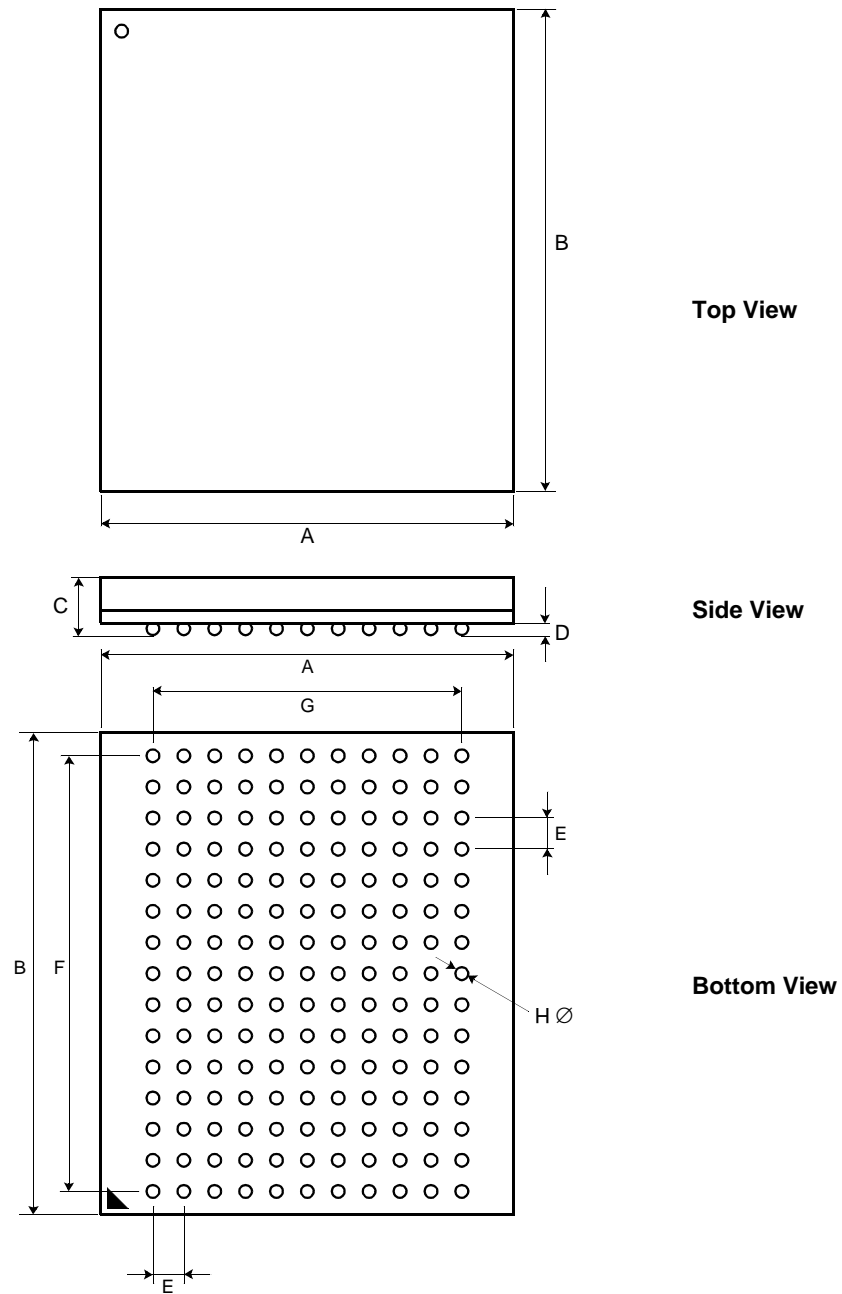
Symbol	Value	Units	Note	Symbol	Value	Units	Note
A	13 ± 0.1	mm		**E**	1.0	mm	
B	15 ± 0.1	mm		**F**	14.0	mm	
C	1.3 ± 0.1	mm		**G**	10.0	mm	
D	0.35 ± 0.05	mm		**H**	0.45 ± 0.05	mm	

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